

**Task 8.1**

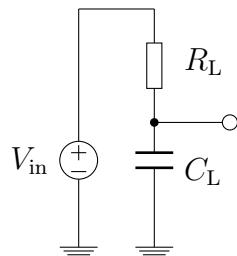
Calculate the power consumption of a pseudo NMOS inverter in its logical zero. Given  $V_{OL} = 0.1V$  and  $W_N/L_n = 9$  in  $0.13\mu m$  technology ( $\mu_n = 270\text{cm}^2/\text{Vs}$ ,  $C_{ox} = 1.6\mu\text{F}/\text{cm}^2$ ,  $V_{TN} = 0.4V$ ,  $V_{DD} = 1.2V$ ,  $L = 100\text{nm}$ ,  $E_{CN}L_N = 0.6V$ ,  $v_{sat} = 8 \cdot 10^6\text{cm/s}$ ).

**Task 8.2**

Calculate the power consumed on a chip:

- The chip has 10M gates, an activity factor of 10%,  $V_{DD} = 1.8V$ , a clock frequency of 500MHz and an average capacity per node of 20fF.
- The chip has 50M gates, an activity factor of 5%,  $V_{DD} = 1.2V$ , a clock frequency of 1GHz and an average capacity per node of 10fF.

Explain which design is the better one and why?

**Task 8.3**

**Figure 8.1:** RC Circuit

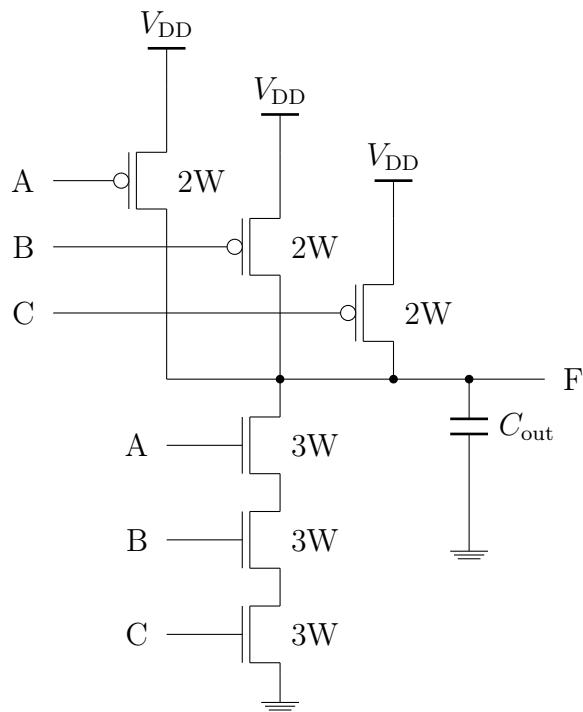
Determine the total energy for the RC circuit in Fig. 8.1. This is transferred from the voltage source to the circuit when there is a jump from 0 to  $V_{DD}$ . Calculate the energy stored by the capacitor. What happens to the rest?

**Task 8.4**

Calculate  $R_{eqn}$  and  $R_{eqp}$  in  $0.13\mu m$  technology ( $\mu_n = 270\text{cm}^2/\text{Vs}$ ,  $\mu_p = 70\text{cm}^2/\text{Vs}$ ,  $C_{ox} = 1.6\mu\text{F}/\text{cm}^2$ ,  $V_{TN} = 0.4V$ ,  $V_{TP} = -0.4V$ ,  $V_{DD} = 1.2V$ ,  $L = 100\text{nm}$ ,  $E_{CN}L_N = 0.6V$ ,  $E_{CP}L_P = 2.4V$ ,  $v_{sat} = 8 \cdot 10^6\text{cm/s}$ ).

**Task 8.5**

Determine the worst case capacities for the NAND3 in Fig. 8.2. Consider common areas for source and drain and specify the result depending on  $C_g$  and  $C_{eff}$ .

**Figure 8.2:** NAND3 Gate**Task 8.6**

A CMOS inverter has a pull-up transistor with  $8\lambda:2\lambda$  and a pull-down transistor with  $4\lambda:2\lambda$ . The inverter should be able to drive four identical inverters. Calculate all capacities in  $0.18\mu\text{m}$  technology ( $\mu_n = 270\text{cm}^2/\text{Vs}$ ,  $\mu_p = 70\text{cm}^2/\text{Vs}$ ,  $C_{ox} = 1\mu\text{F}/\text{cm}^2$ ,  $V_{TN} = 0.5\text{V}$ ,  $V_{TP} = -0.5\text{V}$ ,  $V_{DD} = 1.8\text{V}$ ,  $L = 200\text{nm}$ ,  $E_{CN}L_N = 1.2\text{V}$ ,  $E_{CP}L_P = 4.8\text{V}$ ,  $v_{sat} = 8 \cdot 10^6\text{cm/s}$ ), line capacitances are neglected.

**Task 8.7**

Specify the structure (schematic of building blocks (gates)) of a positive edge controlled RS-FF. Set up the switching sequence table. In addition, enter a positive edge-controlled D-FF. How can the input capacitance be reduced?